KPT-2012YC

2.0 x 1.25 mm SMD Chip LED Lamp

DESCRIPTION

 The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode

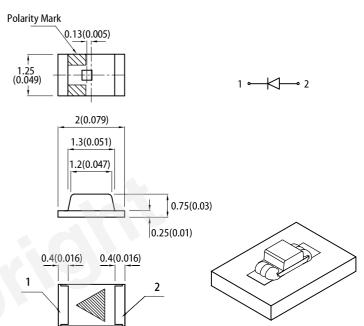
FEATURES

- 2.0 mm x 1.25 mm SMD LED, 0.75 mm thickness
- Low power consumption
- Wide viewing angle
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- · Halogen-free
- · RoHS compliant

APPLICATIONS

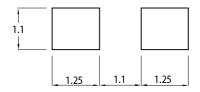
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : \pm 0.1)



Notes

All dimensions are in millimeters (inches).
 Tolerance is ±0.1(0.004") unless otherwise noted.

3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color	Lens Type	lv (mcd) @	lv (mcd) @ 20mA ^[2] Min. Typ.	Viewing Angle ^[1]	
Fait Number	(Material)	Lens Type	Min.	Тур.	201/2	
KPT-2012YC	Yellow (GaAsP/GaP)	Water Clear	3	8	160°	

Notes

01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity / luminous flux: +/-15%.
 Luminous intensity value is traceable to CIE127-2007 standards.

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ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Deveneter	Symphol	Emitting Color	Va	Value	l la it
Parameter	Symbol	Emitting Color	Тур.	Max.	Unit
Wavelength at Peak Emission I_F = 20mA	λ_{peak}	Yellow	590	-	nm
Dominant Wavelength I _F = 20mA	λ_{dom} ^[1]	Yellow	588	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Yellow	35	-	nm
Capacitance	С	Yellow	20	-	pF
Forward Voltage I _F = 20mA	$V_F^{[2]}$	Yellow	2.1	2.5	v
Reverse Current ($V_R = 5V$)	I _R	Yellow	-	10	μΑ
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C $\leq T \leq 85^\circ C$	$TC_{\lambda peak}$	Yellow	0.12	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C $\leq T \leq 85^\circ C$	$TC_{\lambda dom}$	Yellow	0.07	-	nm/°C
Temperature Coefficient of $~V_F$ I_F = 20mA, -10 $^{\circ}C \leq T \leq 85 ^{\circ}C$	TCv	Yellow	-2	-	mV/°C

Notes:

The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.)
 Forward voltage: ±0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	75	mW
Reverse Voltage	V _R	5	V
Junction Temperature	Tj	110	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{stg}	-40 to +85	°C
DC Forward Current	١ _F	30	mA
Peak Forward Current	I _{FM} ^[1]	140	mA
Electrostatic Discharge Threshold (HBM)	-	8000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	540	°C/W
Thermal Resistance (Junction / Solder point)	$R_{th}_{JS}^{[2]}$	350	°C/W

Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{th. JA}, R_{th. JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

Forward Current vs.

Forward Voltage

T_a = 25 °C

1.7 1.9

50

40

20

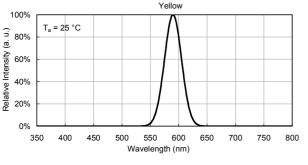
10

0

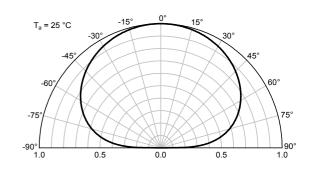
1.5

Forward current (mA) 30

RELATIVE INTENSITY vs. WAVELENGTH



SPATIAL DISTRIBUTION



YELLOW

Luminous Intensity vs.

Forward Current

T_a = 25 °C

10 20 30 40

Forward current (mA)

2.5

2.0

1.5

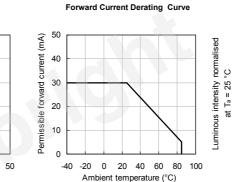
1.0

0.5

0.0

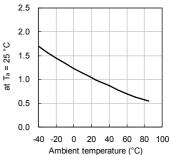
0

Luminous intensity normalised at 20mA



Luminous Intensity vs. Ambient Temperature

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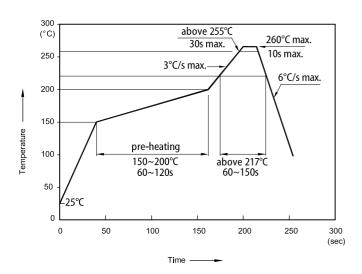


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

2.3 2.5

2.1

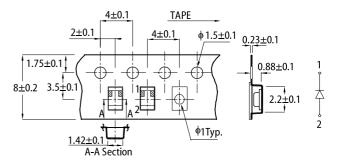
Forward voltage (V)



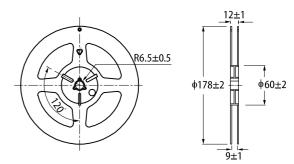
Notes

- Don't cause stress to the LEDs while it is exposed to high temperature.
 The maximum number of reflow soldering passes is 2 times.
 Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

TAPE SPECIFICATIONS (units : mm)



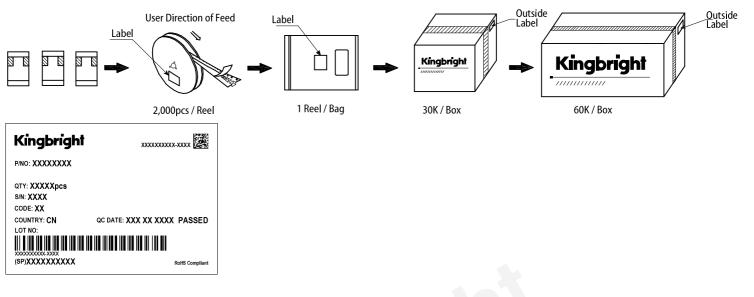
REEL DIMENSION (units : mm)



Spec No: DSAB5603 / 1203001905 Rev No: V.22B Date: 10/11/2021

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PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- 1. 2.
- The information included in this document reflects representative usage scenarios and is intended for technical reference only. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If
- 3.
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